



Material Content Data Sheet



Sales Product Name		TLS715B0NA V50		Issued		28. October 2019		
MA#		MA003062172						
Package		PG-TSNP-7-8		Weight*		8.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.021	12.06	12.06	120598	120598
bumps	noble metal	silver	7440-22-4	0.001	0.01		71	
	non noble metal	tin	7440-31-5	0.033	0.39	0.40	3867	3938
leadframe	non noble metal	zinc	7440-66-6	0.005	0.06		617	
	non noble metal	tin	7440-31-5	0.007	0.08		772	
	non noble metal	chromium	7440-47-3	0.008	0.09		926	
	non noble metal	copper	7440-50-8	2.594	30.63	30.86	306341	308656
encapsulation	organic material	carbon black	1333-86-4	0.014	0.16		1639	
	plastics	epoxy resin	-	0.680	8.03		80333	
leadfinish	inorganic material	silica	-	3.933	46.46	54.65	464509	546481
	noble metal	gold	7440-57-5	0.080	0.95		9496	
	non noble metal	nickel	7440-02-0	0.092	1.08	2.03	10831	20327
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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